

Title (en)

SUBSTRATE WITH AT LEAST TWO METALLIZED POLYMER BUMPS FOR SOLDERED CONNECTION TO WIRING

Title (de)

SUBSTRAT MIT MINDESTENS ZWEI METALLISIERTEN POLYMERHÖCKERN FÜR DIE LÖTVERBINDUNG MIT EINER VERDRAHTUNG

Title (fr)

SUBSTRAT COMPORTANT AU MOINS DEUX SAILLIES DE POLYMERE METALLISEES POUR CONNEXION PAR BRASAGE AVEC UN CABLAGE

Publication

**EP 1186031 A1 20020313 (DE)**

Application

**EP 00938553 A 20000511**

Priority

- DE 0001497 W 20000511
- DE 19923247 A 19990520

Abstract (en)

[origin: WO0072378A1] A substrate (S) with at least two metallized polymer bumps (PS), especially a polymer stud grid array, is configured in such a way that the polymer bumps (PS) have at least one step (ST) and at least one elevation (E). The geometry of the solder bumps (PS) ensures that the soldered connections to the wiring (V) are secure and guarantees reproducible layer thickness for the solder (L).

IPC 1-7

**H01L 23/13**; H01L 23/498; H05K 3/34

IPC 8 full level

**H01L 21/60** (2006.01); **H01L 23/13** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP KR)

**H01L 23/13** (2013.01 - EP KR); **H05K 3/3436** (2013.01 - EP); **B29L 2031/3493** (2013.01 - EP); **H01L 2924/0002** (2013.01 - EP); **H01L 2924/12044** (2013.01 - EP); **H05K 2201/09045** (2013.01 - EP); **H05K 2201/09845** (2013.01 - EP); **Y02P 70/50** (2015.11 - EP)

C-Set (source: EP)

**H01L 2924/0002** + **H01L 2924/00**

Citation (search report)

See references of WO 0072378A1

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**WO 0072378 A1 20001130**; CN 1352805 A 20020605; EP 1186031 A1 20020313; JP 2003500858 A 20030107; KR 100426044 B1 20040406; KR 20020005753 A 20020117; TW 465263 B 20011121

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